



## Development of Electroplated Magnetic Materials for MEMS

N. V. Myung

MEMS Technology Group

Jet Propulsion Laboratory

California Institute of Technology



#### Overview

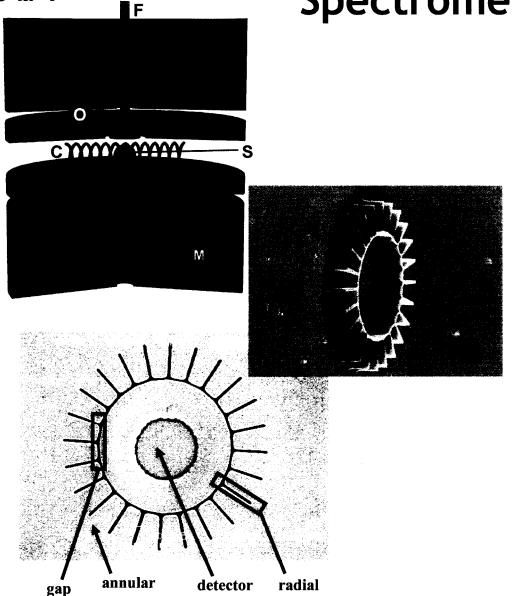


- Examples of magnetic MEMS
- Electrodeposited soft magnetic materials
- Electrodeposited hard magnetic materials
- Nanoengineered magnetic materials
- FDNMR



JPL's Force-Detected NMR
Spectrometer





slit

magnet

magnet

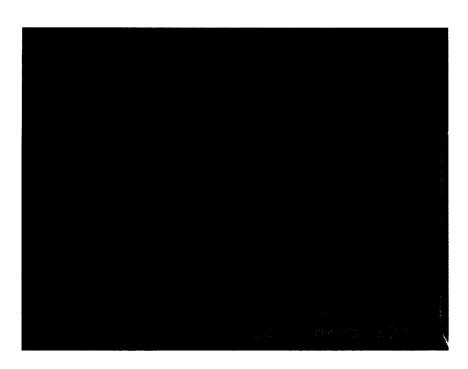
Force-Detected NMR for *In-Situ* Ananlysis

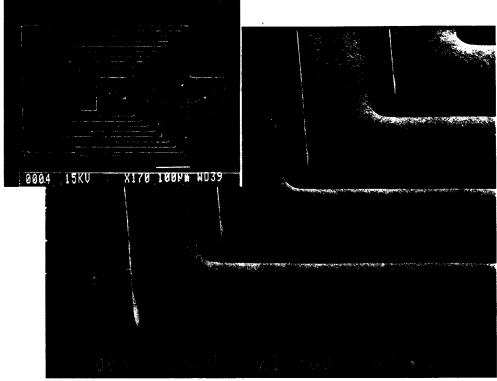
- Study single crystals, organic layers, and mineral phases from corers and drills
- Lightweight, low power;
   Can include multiple devices on one vehicle, or deploy in penetrators
- MEMS fabrication produces many devices at once;
   Easy redundancy and feasible parallel analysis on and off earth

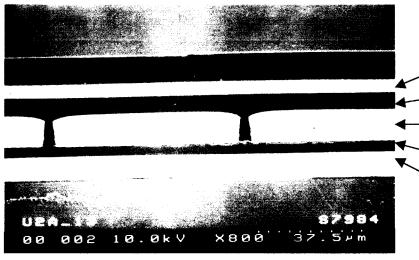


### JPL's microinductor









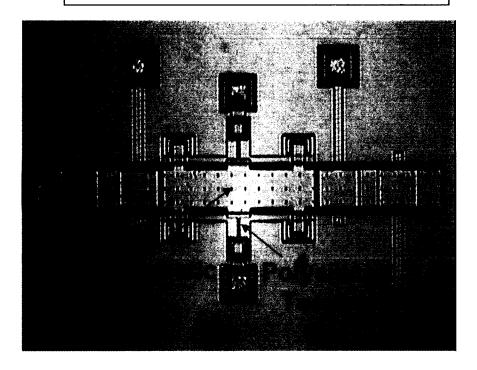
Permalloy
SU-8 resist
Copper Coils
Polyimide Dielectric
Permalloy

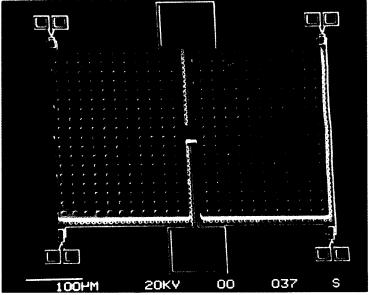


### UCLA Low Power Shock Resistive MEMS Magnetometer



MUMPs fabricated torsion beams and plates with electroplated Magnetic Materials. Pictures taken after full release of the chip.



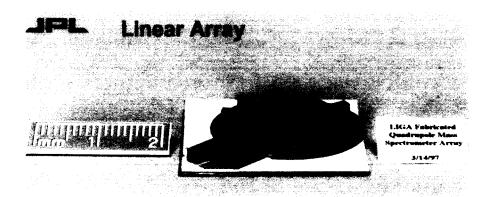


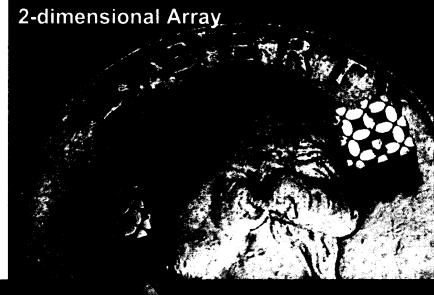


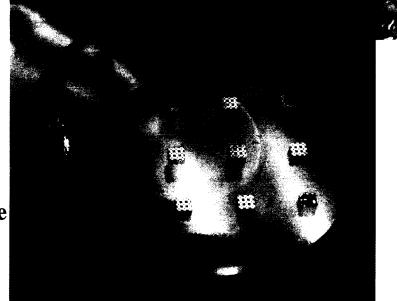


### JPL's LIGA Fabricated Quadrupole Mass Filter for Miniature GC/MS





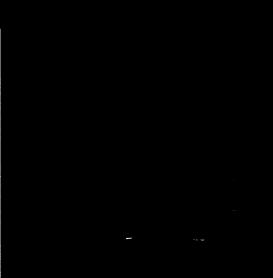




Pole Length: 3 mm pole

# of poles : 24 poles
# of quadrupole: 9

Quadrupole

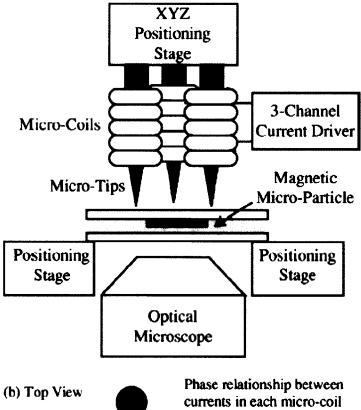


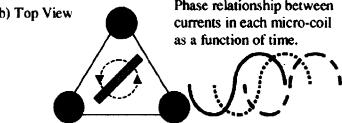


### Electromagnetic Micromotors for Microfluidics Application

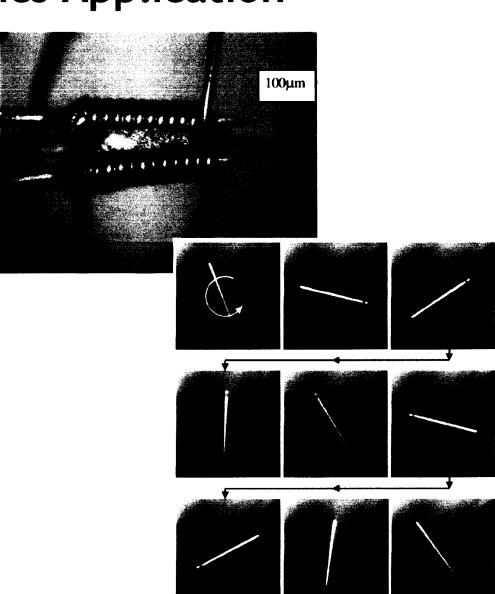








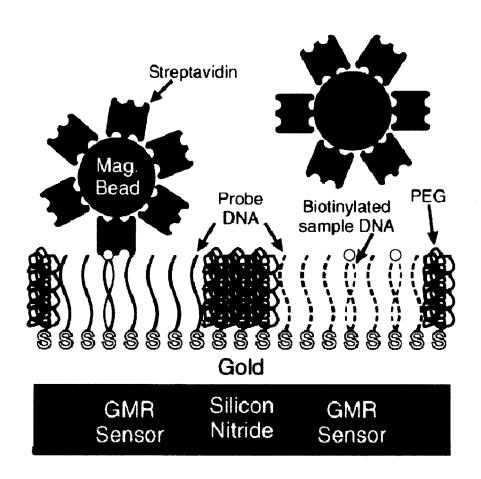
Barbic et al. Appl. Phys. Lett. 79(9),1399 (2001)



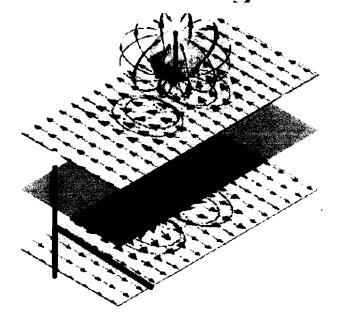


### Magentic Biosensors





 Small magnetic particles used to "tag" a biological or chemical agents





### Requirements for Magnetic MEMS



- Good Magnetic Properties
- Good Adhesion
- Low Stress
- Thermal Stability
- No contamination ICs
- Corrosion Resistance (i.e. HF)
- Ability to deposit variable thicknesses
  - (submicron to mm)



### Why Electrodeposited Magnetic Materials ????



#### **FLEXIBILITY**

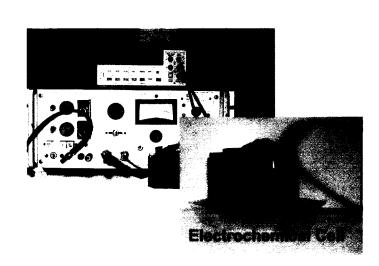
Room Temperature, Ambient Pressure

#### **LOW-COST**

- Easily scaled up
- Lower energy requirement
- Low equipment costs
- Lower production costs

#### **QUALITY**

 Tailored magnetic properties by controlling microstructure and film composition





### **Soft Magnetic Materials**



### Requirements:

- High Magnetic Saturation (M<sub>S</sub>)
- Low coercivity (H<sub>C</sub>)
- Optimal anisotropy field (H<sub>k</sub>) for high permeability
- Good corrosion resistance
- High electrical resistivity (ρ)



### ED Iron-Group alloys with high M<sub>s</sub>



Material	Magnetic		
	Saturation (T)	(Oe)	stricition
NI <sub>80</sub> Fe <sub>20</sub>	1	0.3	-0+
Ni <sub>45</sub> Fe <sub>55</sub>	1.6	0.4	+
NIFeCo	0.8-2.4	1	-0+
NiFeCoB	1.5	0.6	
CoNiFeS	1.7	1	+
CoFe	1.9	3	-0+
CoFeB	1	1.9	-0+
CoFeCr	1.7	0.3	-
CoFeNiCr	1.7	0.5	+
CoFeP	1.5	1	-0+
CoFeCu	1.7-2.2	1	-0+
CoFeB	1.2	1	
(electroles			
s)			
CoB	1.2	1	

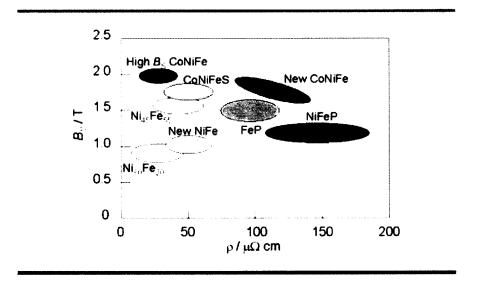
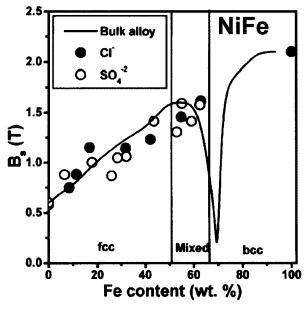


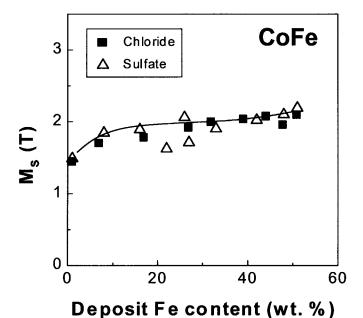
Fig. 1 Soft magnetic materials with high Bs and high  $\rho$  mainly developed by waseda group

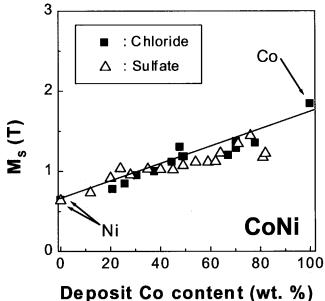


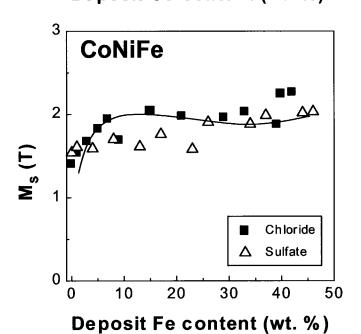
### Magnetic Saturation (M<sub>s</sub>)

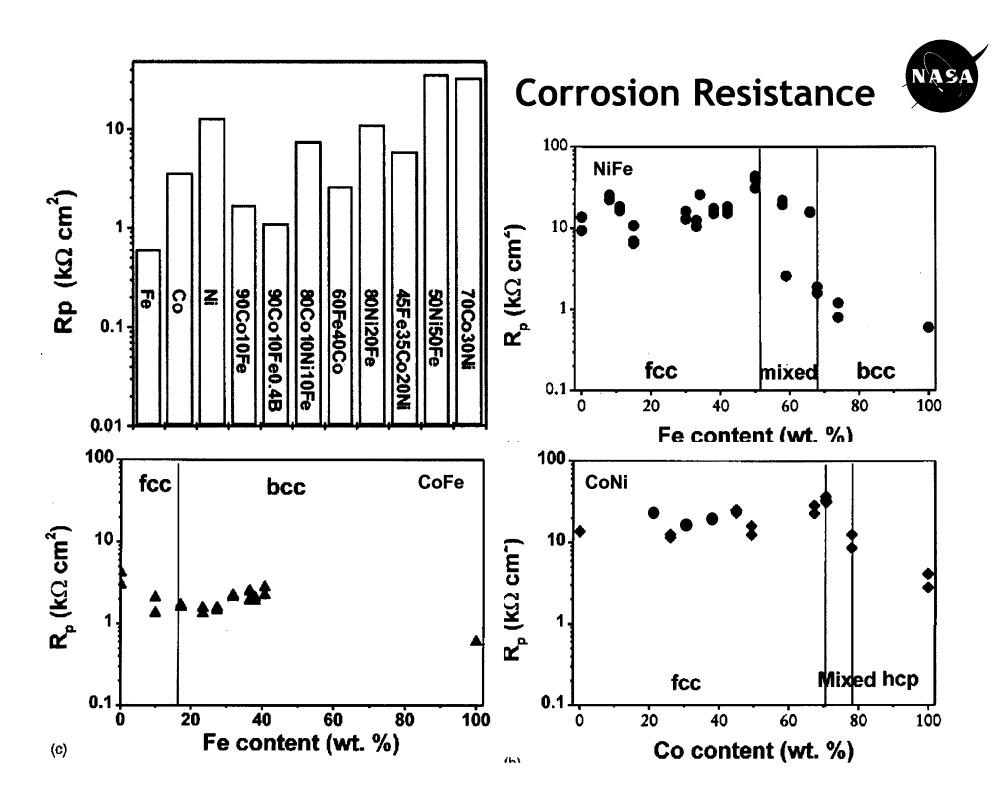










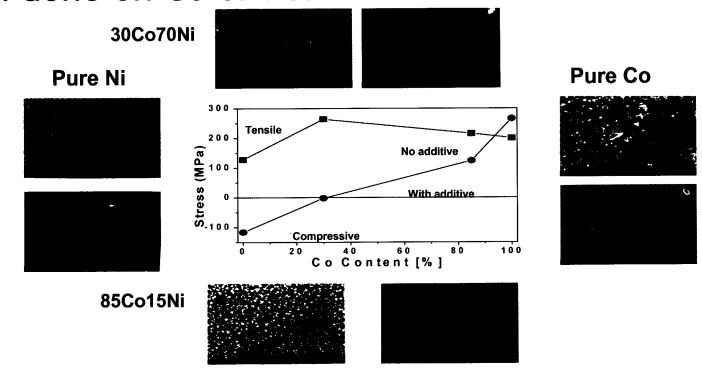




#### Film stress



- Generally, film stress increase with Fe content or Co content
- There are many researches on stress reducer for nickel, however not much of work have been done on Co or Fe.

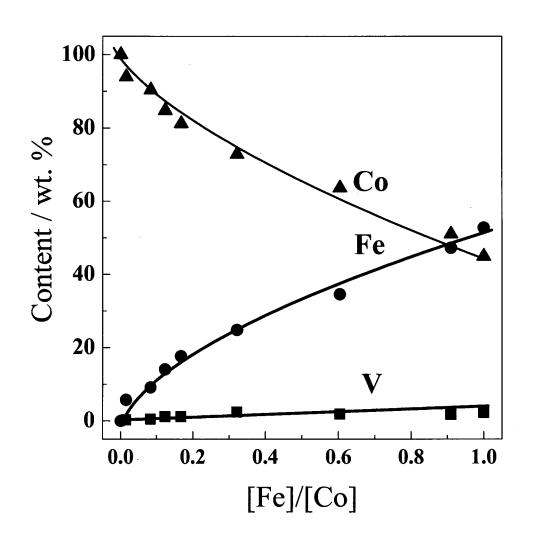


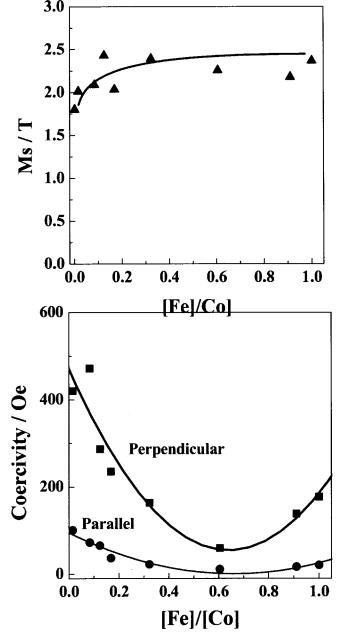


New High Magnetic Saturation Materials Development at UCLA

NASA

(CoFeV)







### Hard Magnetic Materials



### Requirements

- High magnetic saturation (M<sub>S</sub>)
- High remanence (M<sub>R</sub>)
- High BH product (BH<sub>MAX</sub>)
- High coercivity (H<sub>C</sub>)
- High corrosion resistance





### Alloys Elements to Cobalt

<u>VA</u>

Cr Mo

W

<u>VIII</u>

Pd Pt <u>VIB</u>

As

Sb Bi

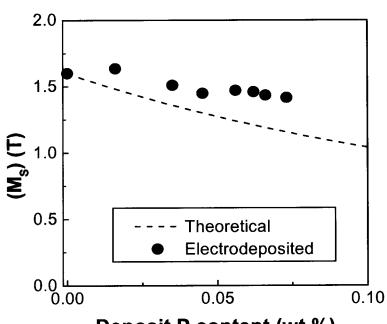
Others Cu

Mn

O

H

# Magnetic Saturation (M<sub>s</sub>) decrease with addition of alloying elements

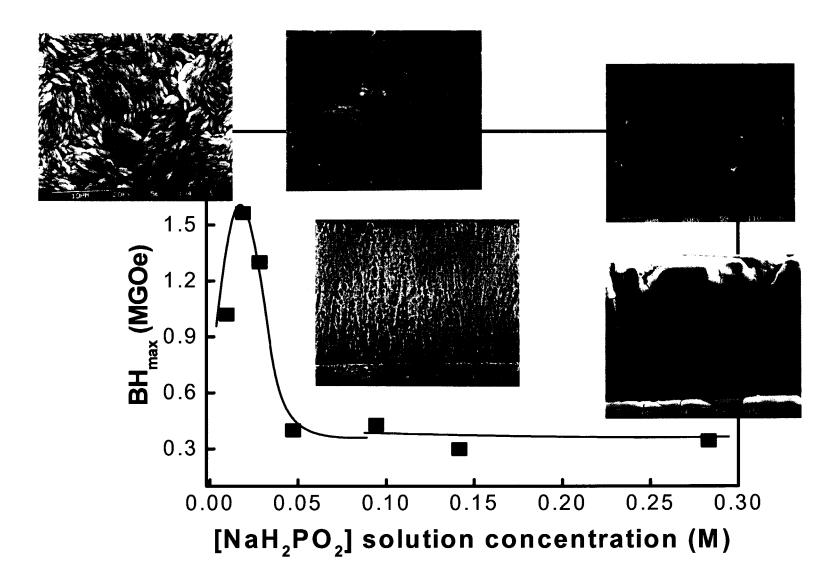


Deposit P content (wt.%)



### BH<sub>max</sub> vs. P contents and [Na H<sub>2</sub>PO<sub>2</sub>]

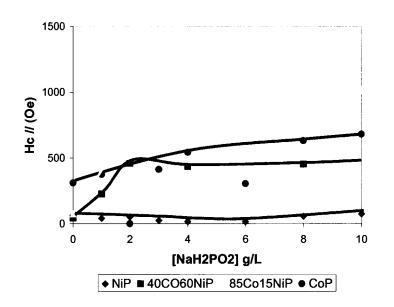


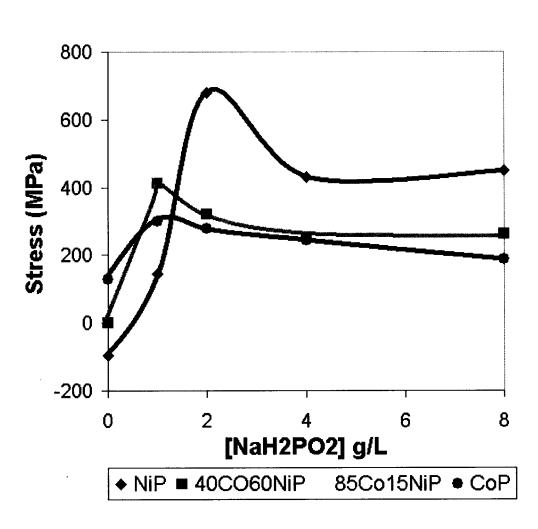




### Film Stress



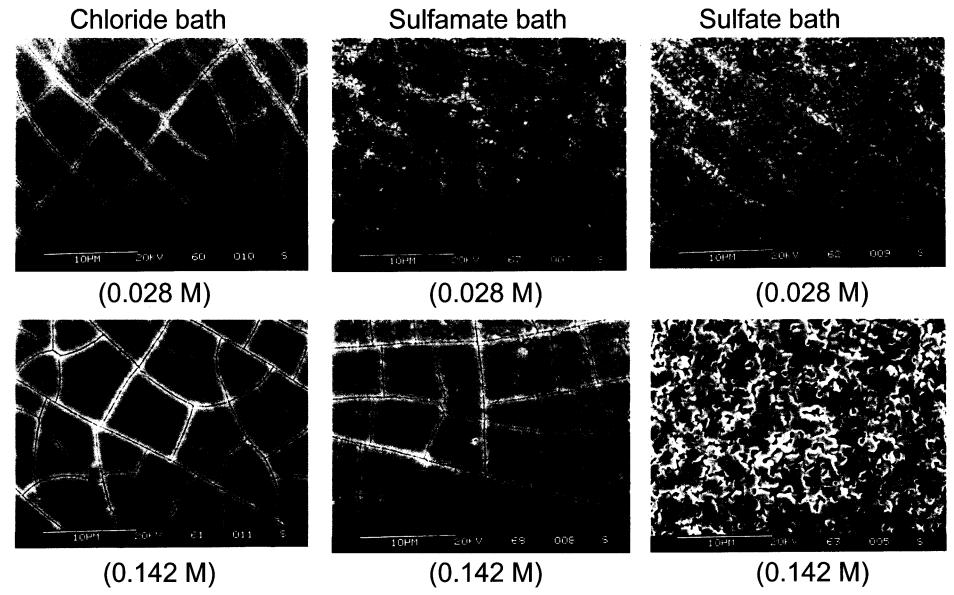






### **SEM** micrographs







### Film Structuring to Minimize Total Film Stress



***************************************	
	economic and property of the control

 Minimizing the film stress and improve corrosion resistance while maintaining the hard magnetic properties by structuring the magnetic films

Hard Magnetic Tensile,	Low Corrosion	Resistance	Layer (	e.g.	CoNiP)
Magnetic Compressive,	High Corrosion	Resistance	Layer (	(e.g.	Ni)



### Magnetic Properties of Electrodeposited Magnetic Films

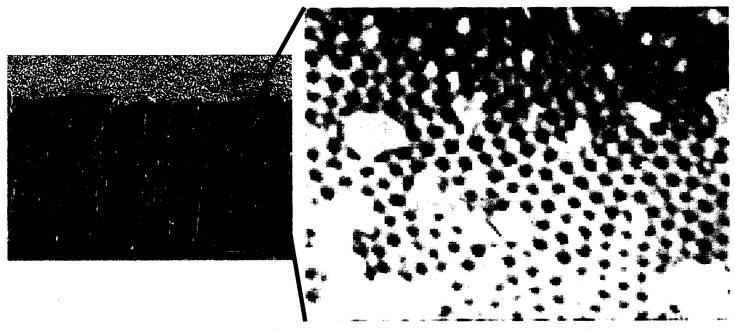


Electrodeposited Alloys	Add Element (wt. %)	Hc (Oe) [Thickness]	Ms (T)	M <sub>R</sub> or S
CoNi	20-40 Ni	100 (//), [2 μm]	1.4- 1.6	0.6-0.775
СоР	2-4 P	1400 (//), 1300 ( <u></u> ), [2 <sub>μ</sub> m]	1.5- 1.6	0.2-0.5 (//) 0.1-0.3 (⊥)
CoNiP	18-37 Ni, 1-3 P	926 (//), 2150 ( <u></u> ), [2 <sub>μ</sub> m]	1.2- 1.4	0.2-0.45 (//) 0.1-0.3 ( <u></u> )
CoMnP	2-4 P, <1 Mn	800 (//), 2000 (⊥), [2 μm]	1.4- 1.5	0.1-0.3 (//) 0.1-0.2 ( <u></u> _)
CoW	12-44 W	400 (//) [0.1 <sub>μ</sub> m]	1.0- 1.5	0.2-0.5
Co₃W/CoW	30-40W	250 (//) [2 <sub>μ</sub> m]	1.2- 1.3	0.2-0.5
CoPtP	30 Pt* 3 P*	2620 (//), 2940 ( <u></u> ) [10 μm]	1	0.4-0.6 (//) 0.3-0.4 ( <u></u> )
Co/Cu	5-50 Cu	340 (//), 650 ( <u></u> ) [2 <sub>µ</sub> m]	0.7- 1.3	0.6-0.7 (//) 0.1-0.2 (⊥)



### Nano-engineered Materials

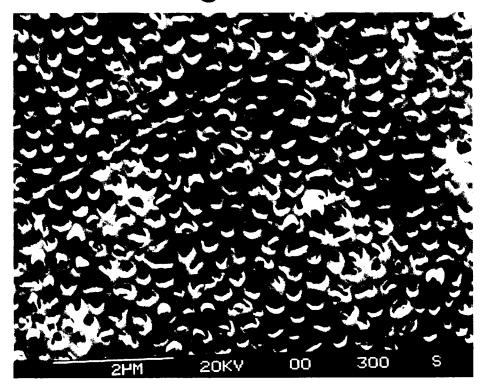




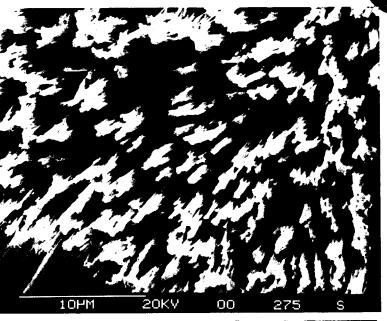
- Nanoengineered magnetic properties
  - Magnetic properties strongly influence by size in nanoscale
- Filled the nanotemplate with magnetic materials to produce
  - nanowires, nanodots, CPP GMR nanostructured nanowires

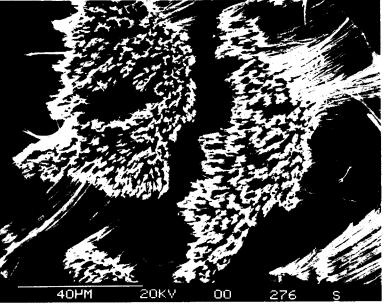


### Filled Aluminum Template with Magnetic Material



### **CoNiP**



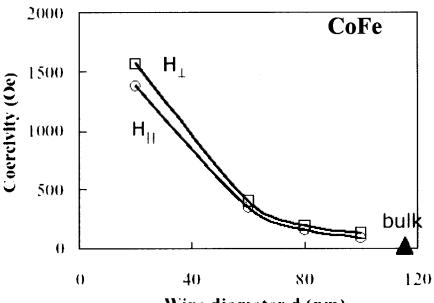




### Nanoengineering magnetic properties

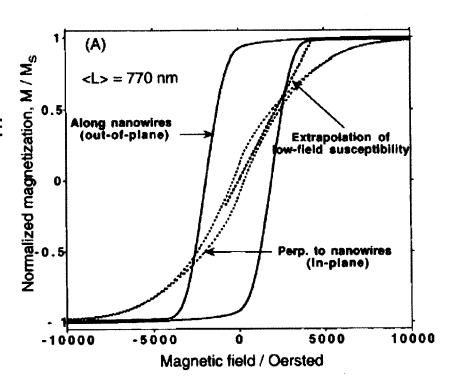


- Coercivity increase with decrease in nanowire diameter (finite size effect)
- Squareness increase with decrease in nanowire diamte (shape anisotropy)



Wire diameter d (nm)

John Hopkins University

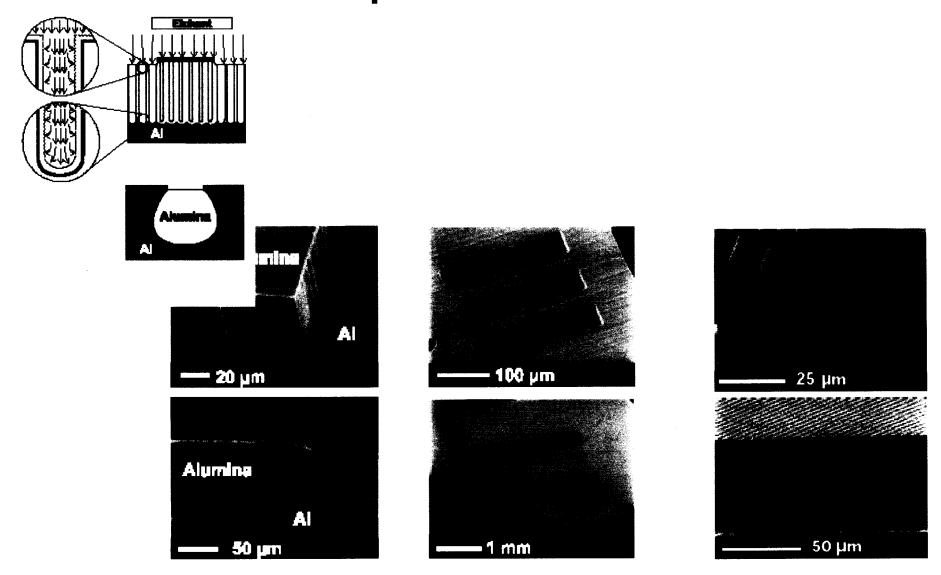


R. M. Metzger et al. IEEE Trans Magn. 36, 30-35 (2000).



### Magnetic Material-Ceramic Composites MEMS





D. Routkevitch, Nano Materials Research LLC. www.nrcorp.com



#### **NASA Needs**



- Size, mass and power consumption for devices and instruments are severely constrained on space missions.
- Given the prohibitive costs of launching any payload into space (between \$10,000 \$1000,000 per kg, depending on the type of mission), the trend during the past decade has been towards "Smaller, faster and cheaper" space missions. Such missions are necessarily of the "micro-spacecraft" class (under 100 kg mass).

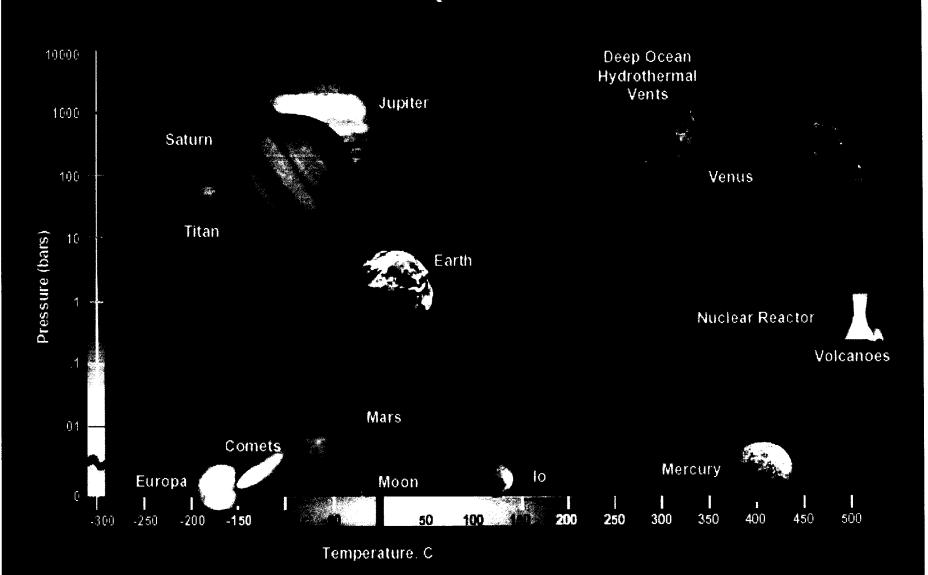


### Some Important Considerations for In situ NASA Instruments Used in NASA Applications

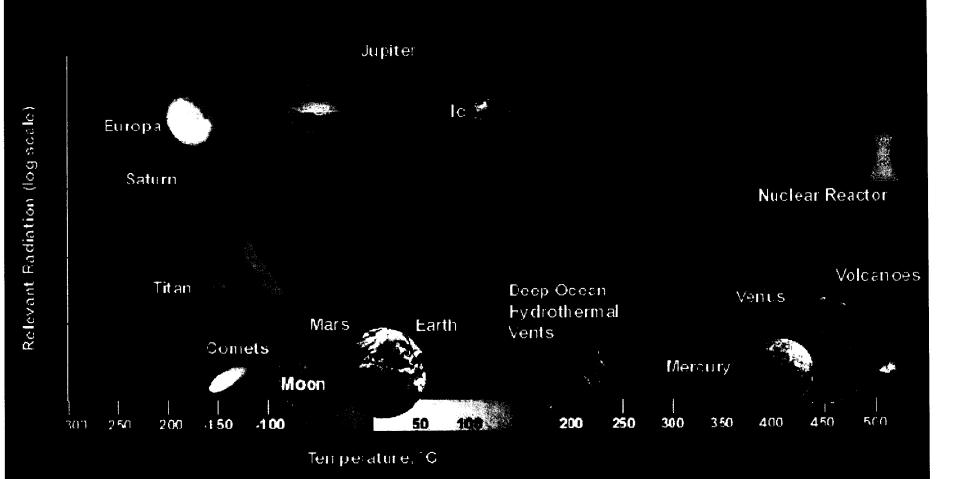


- Low Power
- Low mass
- Low volume (for space applications)
- High reliability
- Long lifetime (sometimes as long as a decade)
- Manageable data rate
- Easily calibrated
- Must have compatible sample handling mechanisms
- Able to withstand extreme environments
- Able to withstand launch loads

### Planetary Extremes



### Planetary Extremes





#### Motivation



#### **Nuclear Magnetic Resonance (NMR) Spectroscopy**

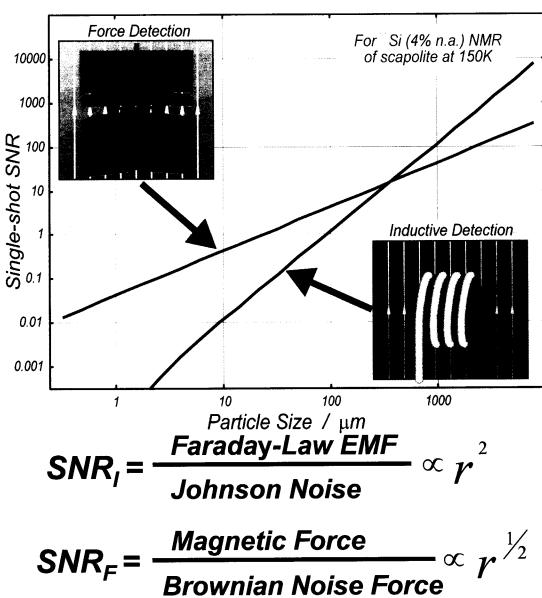
- •Highly specific chemical information: identification of atomic elements, chemical bonding & reactions
- Can detect <sup>1</sup>H and light nuclei; detection/distinction of H<sub>2</sub>O & organics as well as minerals
- Non destructive to sample
- Imaging down to micron scale and below
- Higher sensitivity with force detection than Faraday-law detection at 0.5 mm length scale and below



#### Force-Detected NMR for In-Situ Ananlysis

- Study single crystals, organic layers, and mineral phases from corers and drills
- Lightweight, low power;
   Can include multiple devices on one vehicle, or deploy in penetrators
- MEMS fabrication produces many devices at once;
   Easy redundancy and feasible parallel analysis on and off earth

### Pensitivity Comparison: Force-Detection vs. Name of the Comparison of the Comparison

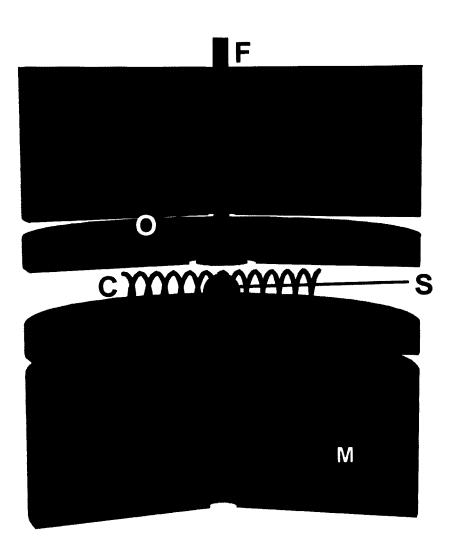




### Force-Detected NMR Spectrometer



- Detector magnet D mounted on Si oscilla beam O interacts sample S via dir force.
- Coil C and to sample
- Fibers Corneter F details Cornetions.
- > R provide ous field across
  - manent pole magnets P merate NMR (B<sub>0</sub>) field.





### Design Goals for MEMS FDNMR Spectrometer



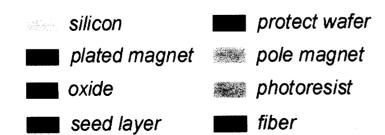
- B<sub>0</sub> 2 T
- Ambient temperature or cooled
- Optimize for 60 micron samples
- Total mass < 1g, power < 100mW, size</li>
   (single detector portable spectment)
- Field homogeneity better
- $\square$   $\omega_h$  ~ 1 kHz,  $\tau_h$  ~ 1 sec. (6)
- Single detector (



#### Microfabrication Process Overview



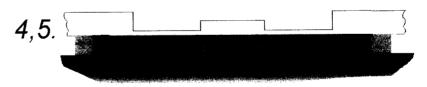
- 1. Thermal oxidation and patterning for oxide sacrificial layer.
- 2. Deposit Cr/Au (200Å/1000Å) plating seed layer and pattern photoresist mold.
- 3. Electroplate ring and detector magnets 10 µm thick.
- 4. Protect front side by wax-mounting to wafer.
- 5. Pattern back and create stress buttress and oscillator beam using deep RIE.
- 6. Remove sacrificial oxide (BOE).
- 7. Bond pole magnet and fiber to back.









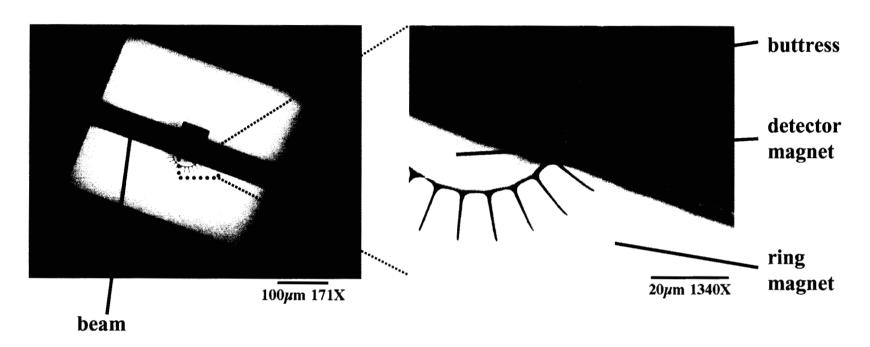






#### Deep RIE-Defined Beam with Plated Magnets

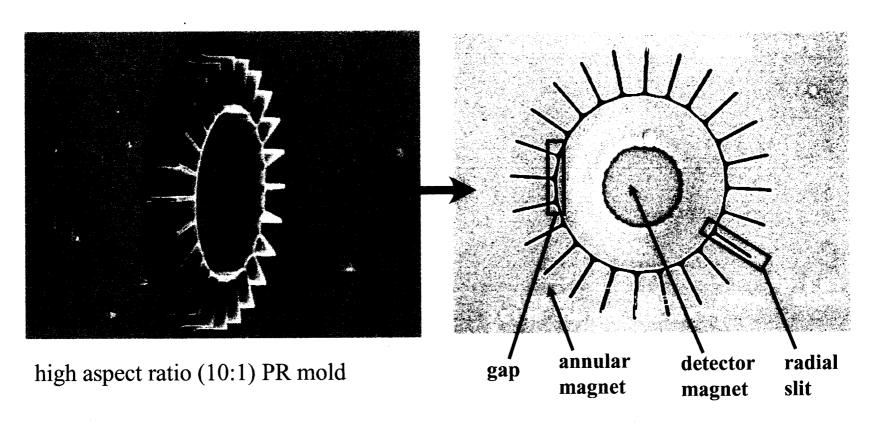




- Novel deep RIE process developed to define 2-6  $\mu$ m-thick Si beam and stress buttress on backside of plated magnet array.
- After removal of PR and oxide sacrificial layer, a free standing beam with a detector magnet is formed. ( $v_h$  ~24-166 KHz, Q~5000 at 50 mTorr)







- The PR mold for electrodeposition defines 1 micron gap between detector and annular magnets and creates eddycurrent-reduction slits.
- 10 micron thick 40Co:60Ni magnets ( $M_s$  = 1.2 T/ $\mu_o$ , 40 Mpa stress) are successfully plated with the 1  $\mu$ m gap and the slits.
- Co:Ni:Fe magnets with  $M_s = 1.8 \text{ T}/\mu_o$  on the way.



### **Conclusions**



- There are many magnetic materials waiting to apply in magnetic MEMS.
- There are many problems to integrate these materials.
- More researches are needed to overcome engineering problems



### Acknowledgements



**UCLA** 

Prof. Ken Nobe

Mr. Morton Schwatz

Dr. D. -Y. Park

Mr. B.-Y. Yoo

Prof. Paulo Sumodjo

Prof. J. W. Judy

Prof. C.-K. Yang

**JPL** 

Dr. Thomas George

Dr. Kyung-ah Son

Mr. Daniel Miller

Dr. W. Tang

Caltech

Prof. D. P. Weitekamp

Dr. L. A. Madsen,

Mr. G. M. Leskowitz



**NASA Code R** 



DARPA MEMS Program:

DABT63-99-1-0020



NSF XYZ on a Chip